

Shunt Resistor Specification



Document No: SR1206STD001A

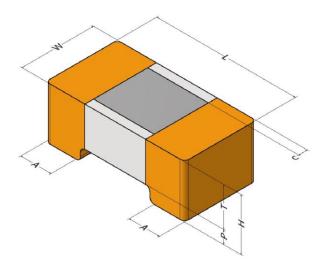
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Scope

This specification applies of metal foil current shunt resistor rectangular type.

Dimensions



Туре		N//matarial)				
(inch size)	L	W	H A		M(material)	
SR1206	3.2±0.2	1.65±0.2	1.20±0.15	0.80±0.2	MnCuSn	
L30	5.2±0.2	1.05±0.2	1.20±0.15	0.80±0.2	iviiicusii	
SR1206	3.2±0.2	1.65±0.2	0.90±0.15	0.80±0.2	MnCuSn	
L50	5.2±0.2	1.05±0.2	0.90±0.15	0.80±0.2	Milicusii	
SR1206	3.2±0.2	1.65±0.2	0.90±0.15	0.80±0.2	MnCu	
1L0	3.Z <u>I</u> U.Z	1.03IU.2	U.9U±U.15	U.0UIU.Z	iviiicu	

Features

- \blacklozenge 2W up to 81A at 0.3 m Ω
- ◆ Lead free, RoHs compliant for global applications ◆ Current sensor for power hybrid sources and halogen free
- ◆Excellent long term stability

Application

- Power modules
- Frequency converters
- Current sensor for power hybrid sources
- High current for automotive

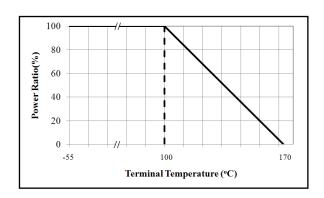


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Derating Curve



Part Numbers

<u>SR 1206 E F F OL30</u>

(1) (2) (3) (4) (5) (6)

(1)Series Name: SR (Shunt Resistor)

(2) Chip size: 1206

(3) Packaging Material: Emboss (E)

(4) Resistance Tolerance: $\pm 1\%$ (F), $\pm 2\%$ (G), $\pm 5\%$ (J)

(5)Power rating: F=2.0W

(6)Resistance Code: Ex: 0L30 means $0.3m\Omega$, etc.

Electrical Specification

Item	Power Rating	Resistance Range(m Ω)	Operation Temp. Range	TCR (PPM/°C)
	06 2W	0.3		±300
SR1206		0.5	-55~+170°C	±200
		1.0		±150



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Performances

Environmental Performance

No.	Item	Test Condition	Specification
1	Short Time Overload	Loading 5 times rate power 5sec	ΔR: ±1%
2	Temperature Coefficient of Resistance (T.C.R.)	+25°C/+125°C. (JIS-C5202-5.2) $TCR \text{ (ppm/°C)} = \frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to electrical specification.
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90~98% percent and a temperature of 25°C / 65°C 10 cycles (MIL-STD-202, Method 106)	ΔR: ±1%
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 170 $^{\circ}$ C for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±1%
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±1%
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55±3°C (30min.)/+125±2°C (30min.) for1000 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature 30 min. 30 min. 30 min. 2~3 mi	ΔR: ±1%



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Function Performance

No.	Item	Test Condition	Specification
1	Bending Strength	Mount the chip to test 90mm(L)*40mm(W) FR4 printed circuit board substrate. Apply pressure in direction of arrow unit band width reaches 2mm(+0.2/-0mm) illustrated in the figure below and hold for 10±1 sec. (JIS-C5202-6.1) Unit: mm Position before bend Testing printed circuit board	ΔR: ±1%
2	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath 235 \pm 5°C for 2 \pm 0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5 202-6.11) Molten solder Specimen SMID $h = 10 \text{ mm}$ $H = 10 \text{ mm}$ min.	Solder shall be covered 95% or more of the electrode area.

Remark:

All Reliability test should follow De-rating curve , terminal temperature of component should be below $100\,^{\circ}$.



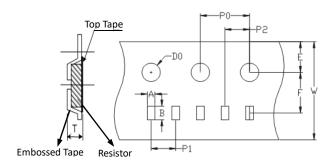


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Tape Packaging Specifications

◆Embossed Plastic Tape Specifications



Туре		Carrier Dimensions (mm)								
Туре	Α	В	E	F	W	P0	P1	P2	D0	Т
1206	1.88±0.1	3.56±0.1	1.75±0.1	3.50±0.05	8.00±0.1	4.00±0.1	4.00±0.1	2.00±0.05	1.55±0.05	1.40±0.1

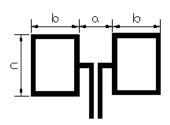
Packaging

Size EIA (EIAJ)	1206
Standard Packing Quantity (pcs /reel)	2,000

Storage Conditions

Temperature : 22^28° C, Humidity : $40^75\%$

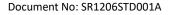
Recommended Pad Layout



Туре	Pad Layout Dimension (mm)				
	а	b	С		
1206	1.4	1.7	1.8		

Note. pad size, solder insufficient, excessive solder, solder void and component shifted will affect the resistance accuracy after IR reflow. Circuit calibration is a must to be done by functional test.

Soldering Recommendations

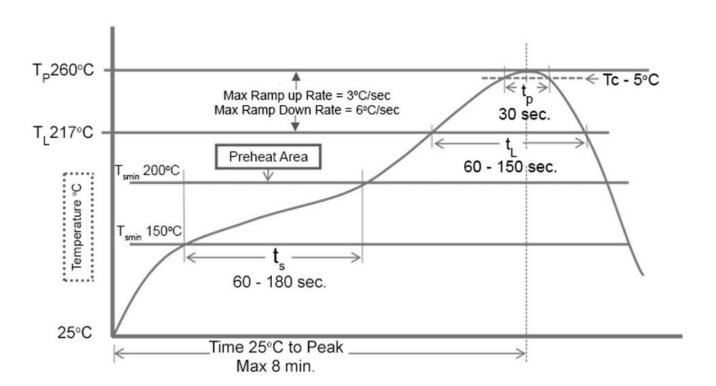




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- ◆ Peak reflow temperatures and durations:
 - IR Reflow Peak = 260° C max for 10 sec
 - Not suitable for wave soldering
- ◆ Recommended IR Reflow Profile:



ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.